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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	18144
Number of Logic Elements/Cells	-
Total RAM Bits	165888
Number of I/O	418
Number of Gates	1000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	624-BCLGA
Supplier Device Package	624-CLGA (32.5x32.5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax1000-lg624m

Thermal Characteristics

Introduction

The temperature variable in Microsemi's Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature. EQ 1 can be used to calculate junction temperature.

T_J = Junction Temperature = $\Delta T + T_a$

EQ 1

Where:

T_a = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient

$\Delta T = \theta_{ja} * P$

EQ 2

Where:

P = Power

θ_{ja} = Junction to ambient of package. θ_{ja} numbers are located under Table 2-6 on page 2-7.

Package Thermal Characteristics

The device junction-to-case thermal characteristic is θ_{jc}, and the junction-to-ambient air characteristic is θ_{ja}. The thermal characteristics for θ_{ja} are shown with two different air flow rates. θ_{jc} values are provided for reference. The absolute maximum junction temperature is 125°C.

The maximum power dissipation allowed for commercial- and industrial-grade devices is a function of θ_{ja}. A sample calculation of the absolute maximum power dissipation allowed for an 896-pin FBGA package at commercial temperature and still air is as follows:

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. } (°C) - \text{Max. ambient temp. } (°C)}{\theta_{ja}(°C/W)} = \frac{125°C - 70°C}{13.6°C/W} = 4.04\ W$$

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc}.

Table 2-6 • **Package Thermal Characteristics**

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP)[1]	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA)[2]	624	6.5	8.9	8.5	8	°C/W

Notes:

1. *θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.*
2. *θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.*

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • **Temperature and Voltage Timing Derating Factors (Normalized to Worst-Case Commercial, T_J = 70°C, VCCA = 1.425V)**

	Junction Temperature						
VCCA	–55°C	–40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

1. *The user can set the junction temperature in Designer software to be any integer value in the range of –55°C to 175°C.*
2. *The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.*

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

Timing Characteristics

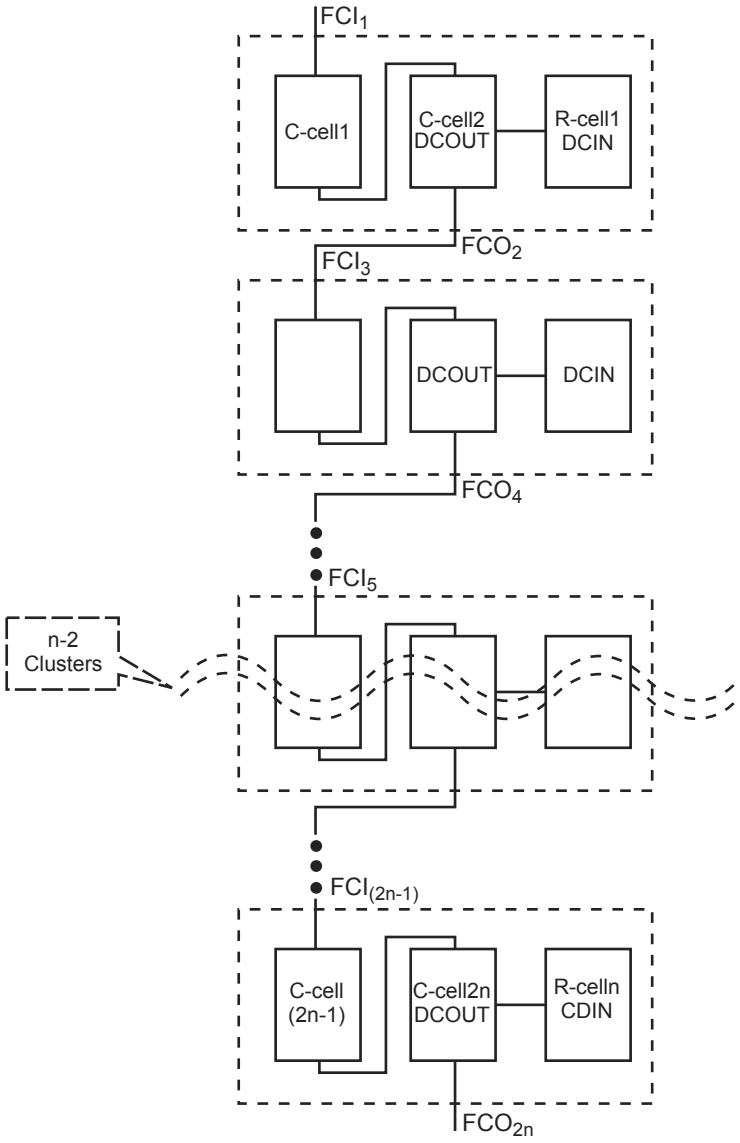
***Table 2-25* • 2.5V LVCMOS I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS25 I/O Module Timing								
t_{DP}	Input Buffer		1.95		2.22		2.61	ns
t_{PY}	Output Buffer		3.29		3.74		4.40	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		2.48		2.50		2.51	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.48		2.50		2.51	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		5.74		6.54		7.69	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.60		7.51		8.83	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Timing Characteristics

***Table 2-61* • LVPECL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVPECL Output Module Timing								
t_{DP}	Input Buffer		1.66		1.89		2.22	ns
t_{PY}	Output Buffer		2.24		2.55		3.00	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the IO output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns



Note: The carry-chain sequence can end on either C-cell.

Figure 2-30 • **Carry-Chain Sequencing of C-Cells**

Timing Characteristics

Refer to Table 2-62 on page 2-55 for more information on carry-chain timing.

The ClockTileDist Cluster contains an HCLKMux (HM) module for each of the four HCLK trees and a CLKMux (CM) module for each of the CLK trees. The HCLK branches then propagate horizontally through the middle of the core tile to HCLKColDist (HD) modules in every SuperCluster column. The CLK branches propagate vertically through the center of the core tile to CLKRowDist (RD) modules in every SuperCluster row. Together, the HCLK and CLK branches provide for a low-skew global fanout within the core tile (Figure 2-40 and Figure 2-41).

Figure 2-40 • **CTD, CD, and HD Module Layout**

Figure 2-41 • **HCLK and CLK Distribution within a Core Tile**

PLLRCLK and PLLHCLK

PLLRCLK (PLLHCLK) is used to drive global resource CLK (HCLK) from a PLL (Figure 2-44).

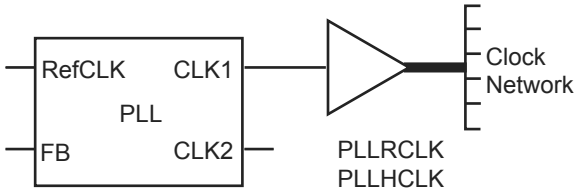


Figure 2-44 • **PLLRCLK and PLLHCLK**

Using Global Resources with PLLs

Each global resource has an associated PLL at its root. For example, PLLA can drive HCLKA, PLLE can drive CLKE, etc. (Figure 2-45).

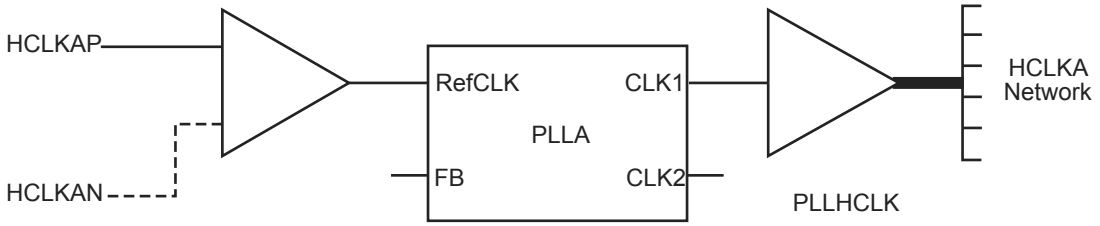


Figure 2-45 • **Example of HCLKA Driven from a PLL with External Clock Source**

In addition, each clock pin of the package can be used to drive either its associated global resource or PLL. For example, package pins CLKEP and CLKEN can drive either the RefCLK input of PLLE or CLKE.

There are two macros required when interfacing the embedded PLLs with the global resources: PLLINT and PLLOUT.

PLLINT

This macro is used to drive the RefCLK input of the PLL internally from user signals.

PLLOUT

This macro is used to connect either the CLK1 or CLK2 output of a PLL to the regular routing network (Figure 2-46).

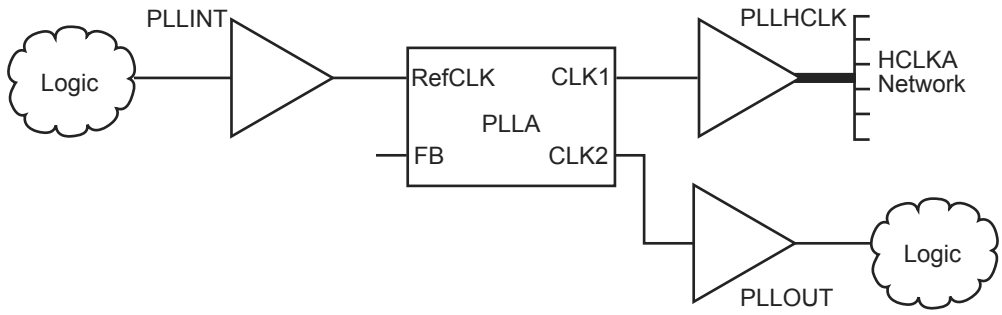


Figure 2-46 • **Example of PLLINT and PLLOUT Usage**

Clock Skew Minimization

Figure 2-56 indicates how feedback from the clock network can be used to create minimal skew between the distributed clock network and the input clock. The input clock is fed to the reference clock input of the PLL. The output clock (CLK2) feeds a routed clock network. The feedback input to the PLL uses a clock input delayed by a routing network. The PLL then adjusts the phase of the input clock to match the delayed clock, thus providing nearly zero effective skew between the two clocks. Refer to the *Axcelerator Family PLL and Clock Management* application note for more information.

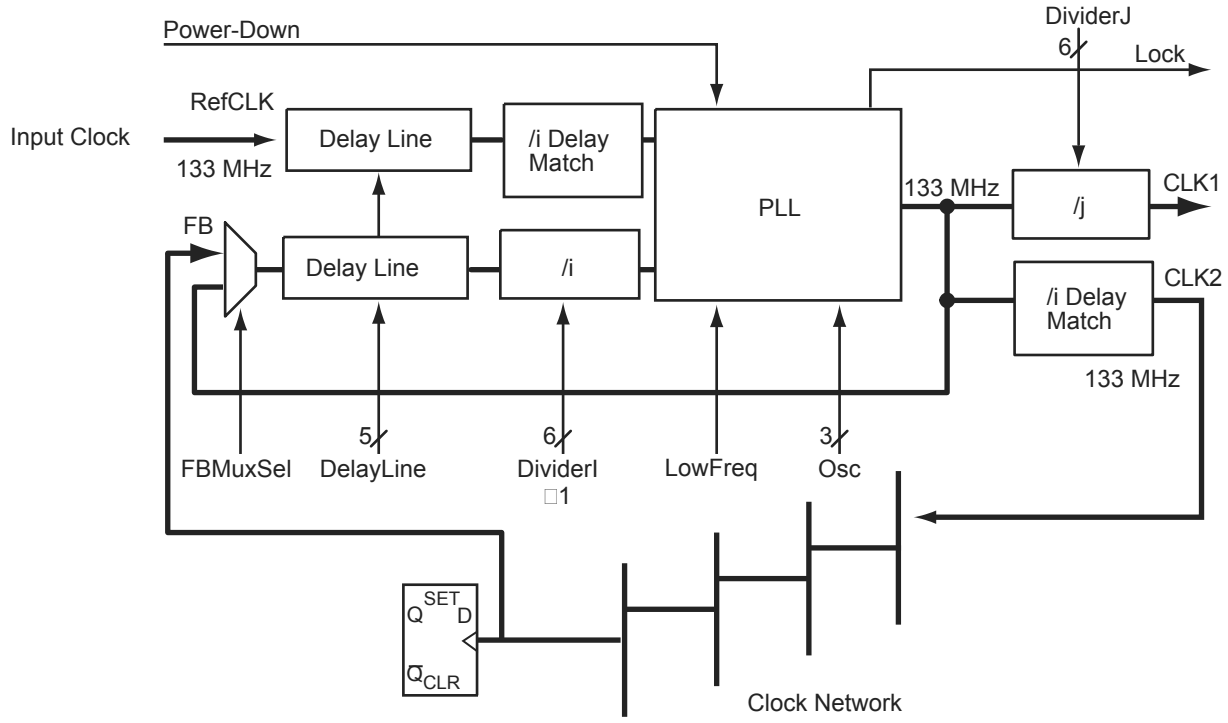


Figure 2-56 • **Using the PLL for Clock Deskewing**

***Table 2-90* • Two RAM Blocks Cascaded**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Write Mode								
t_{WDASU}	Write Data Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WADSU}	Write Address Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WENSU}	Write Enable Setup vs. WCLK		1.39		1.59		1.87	ns
t_{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t_{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t_{WCLK}	WCLK Minimum Low Pulse Width	1.76		1.76		1.76		ns
t_{WCKP}	WCLK Minimum Period	2.51		2.51		2.51		ns
Read Mode								
t_{RADSU}	Read Address Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t_{RENSU}	Read Enable Setup vs. RCLK		1.71		1.94		2.28	ns
t_{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		2.26		2.58		3.03	ns
t_{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t_{RCLKL}	RCLK Minimum Low Pulse Width	1.89		1.89		1.89		ns
t_{RCKP}	RCLK Minimum Period	2.62		2.62		2.62		ns

Note: Timing data for these two cascaded RAM blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

FIFO

Every memory block has its own embedded FIFO controller. Each FIFO block has one read port and one write port. This embedded FIFO controller uses no internal FPGA logic and features:

- Glitch-free FIFO Flags
- Gray-code address counters/pointers to prevent metastability problems
- Overflow and underflow control

Both ports are configurable in various sizes from 4k x 1 to 128 x 36, similar to the RAM block size. Each port is fully synchronous.

Read and write operations can be completely independent. Data on the appropriate WD pins are written to the FIFO on every active WCLK edge as long as WEN is high. Data is read from the FIFO and output on the appropriate RD pins on every active RCLK edge as long as REN is asserted.

The FIFO block offers programmable almost-empty (AEMPTY) and almost-full (AFULL) flags as well as EMPTY and FULL flags (Figure 2-61):

- The FULL flag is synchronous to WCLK. It allows the FIFO to inhibit writing when full.
- The EMPTY flag is synchronous to RCLK. It allows the FIFO to inhibit reading at the empty condition.

Gray code counters are used to prevent metastability problems associated with flag logic. The depth of the FIFO is dependent on the data width and the number of memory blocks used to create the FIFO. The write operations to the FIFO are synchronous with respect to the WCLK, and the read operations are synchronous with respect to the RCLK.

The FIFO block may be reset to the empty state.

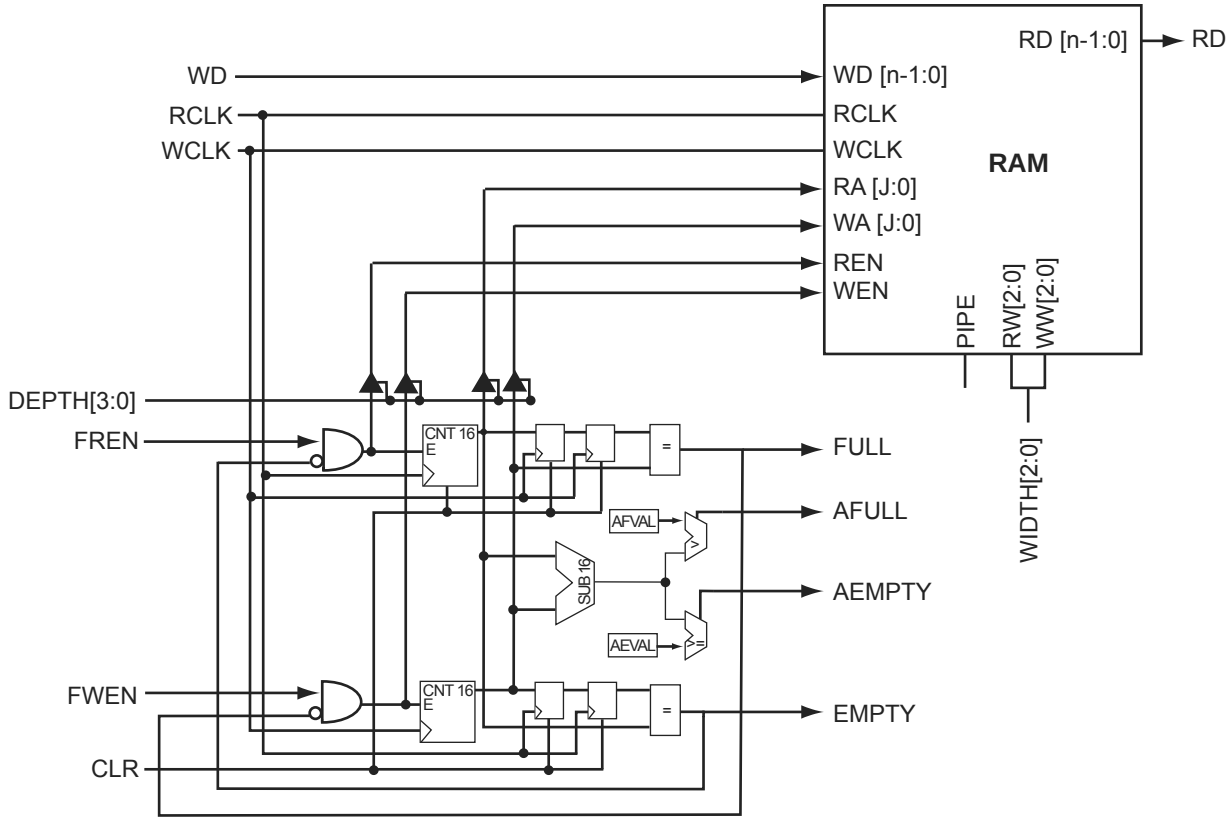


Figure 2-61 • **Axcelerator RAM with Embedded FIFO Controller**

***Table 2-98* • One FIFO Block**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
FIFO Module Timing								
t_{WSU}	Write Setup		11.40		12.98		15.26	ns
t_{WHD}	Write Hold		0.22		0.25		0.30	ns
t_{WCKH}	WCLK High		0.75		0.75		0.75	ns
t_{WCKL}	WCLK Low		0.88		0.88		0.88	ns
t_{WCKP}	Minimum WCLK Period	1.63		1.63		1.63		ns
t_{RSU}	Read Setup		11.63		13.25		15.58	ns
t_{RHD}	Read Hold		0.00		0.00		0.00	ns
t_{RCKH}	RCLK High		0.77		0.77		0.77	ns
t_{RCKL}	RCLK Low		0.93		0.93		0.93	ns
t_{RCKP}	Minimum RCLK period	1.70		1.70		1.70		ns
t_{CLRHF}	Clear High		0.00		0.00		0.00	ns
t_{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t_{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t_{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t_{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
$t_{RCK2RD1}$	RCLK-To-OUT (Pipelined)		1.32		1.51		1.77	ns
$t_{RCK2RD2}$	RCLK-To-OUT (Non-Pipelined)		2.16		2.46		2.90	ns

Note: Timing data for this single block FIFO has a depth of 4,096. For all other combinations, use Microsemi's timing software.

BG729	
AX1000 Function	Pin Number
Bank 0	
IO00NB0F0	E6
IO00PB0F0	F6
IO01NB0F0	G8
IO01PB0F0	G7
IO02NB0F0	D7
IO02PB0F0	E7
IO03NB0F0	D5
IO03PB0F0	E5
IO04NB0F0	G9
IO04PB0F0	H9
IO05NB0F0	E8
IO05PB0F0	F8
IO06NB0F0	C6
IO06PB0F0	D6
IO07NB0F0	B5
IO07PB0F0	C5
IO08NB0F0	A6
IO08PB0F0	A5
IO09NB0F0	E9
IO09PB0F0	F9
IO10NB0F0	G10
IO10PB0F0	H10
IO11NB0F0	B7
IO11PB0F0	B6
IO12NB0F1	C8
IO12PB0F1	C7
IO13NB0F1	E10
IO13PB0F1	F10
IO14NB0F1	G11
IO14PB0F1	H11
IO15NB0F1	D9
IO15PB0F1	D8
IO16NB0F1	A8
IO16PB0F1	A7
IO17NB0F1	B9
IO17PB0F1	B8

BG729	
AX1000 Function	Pin Number
IO18NB0F1	C10
IO18PB0F1	C9
IO19NB0F1	E11
IO19PB0F1	F11
IO20NB0F1	G12
IO20PB0F1	H12
IO21NB0F1	D11
IO21PB0F1	D10
IO22NB0F2	A10
IO22PB0F2	A9
IO23NB0F2	B11
IO23PB0F2	B10
IO24NB0F2	G13
IO24PB0F2	H13
IO25NB0F2	C12
IO25PB0F2	C11
IO26NB0F2	E12
IO26PB0F2	D12
IO27NB0F2	E13
IO27PB0F2	F13
IO28NB0F2	G14
IO28PB0F2	H14
IO29NB0F2	A12
IO29PB0F2	B12
IO30NB0F2/HCLKAN	C13
IO30PB0F2/HCLKAP	D13
IO31NB0F2/HCLKBN	F14
IO31PB0F2/HCLKBP	E14
Bank 1	
IO32NB1F3/HCLKCN	C14
IO32PB1F3/HCLKCP	B14
IO33NB1F3/HCLKDN	D16
IO33PB1F3/HCLKDP	D15
IO34NB1F3	B16
IO34PB1F3	A16
IO35NB1F3	E15
IO35PB1F3	F15

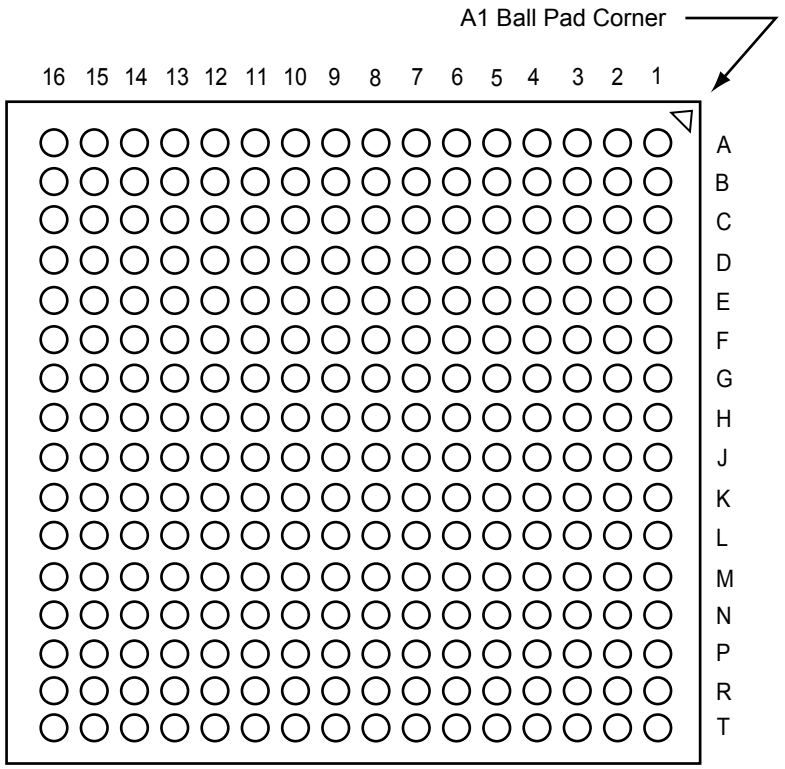
BG729	
AX1000 Function	Pin Number
IO36NB1F3	H15
IO36PB1F3	G15
IO37NB1F3	C17
IO37PB1F3	C16
IO38NB1F3	B18
IO38PB1F3	B17
IO39NB1F3	A18
IO39PB1F3	A17
IO40NB1F3	H16
IO40PB1F3	G16
IO41NB1F4	B19
IO41PB1F4	A19
IO42NB1F4	C19
IO42PB1F4	C18
IO43NB1F4	D18
IO43PB1F4	D17
IO44NB1F4	H17
IO44PB1F4	G17
IO45NB1F4	F17
IO45PB1F4	E17
IO46NB1F4	B20
IO46PB1F4	A20
IO47NB1F4	C21
IO47PB1F4	C20
IO48NB1F4	H18
IO48PB1F4	G18
IO49NB1F4	F18
IO49PB1F4	E18
IO50NB1F4	D20
IO50PB1F4	D19
IO51NB1F4	A22
IO51PB1F4	A21
IO52NB1F4	B22
IO52PB1F4	B21
IO53NB1F4	F19
IO53PB1F4	E19
IO54NB1F5	F20

BG729	
AX1000 Function	Pin Number
IO109NB3F10	V24
IO109PB3F10	V25
IO110NB3F10	T20
IO110PB3F10	T21
IO111NB3F10	W26
IO111PB3F10	W27
IO112NB3F10	U22
IO112PB3F10	U23
IO113NB3F10	Y26
IO113PB3F10	Y27
IO114NB3F10	U20
IO114PB3F10	U21
IO115NB3F10	W24
IO115PB3F10	W25
IO116NB3F10	V22
IO116PB3F10	V23
IO117NB3F10	Y24
IO117PB3F10	Y25
IO118NB3F11	V20
IO118PB3F11	V21
IO119NB3F11	AA26
IO119PB3F11	AA27
IO120NB3F11	W22
IO120PB3F11	W23
IO121NB3F11	AA24
IO121PB3F11	AA25
IO122NB3F11	W20
IO122PB3F11	W21
IO123NB3F11	AB26
IO123PB3F11	AB27
IO124NB3F11	Y22
IO124PB3F11	Y23
IO125NB3F11	AB24
IO125PB3F11	AB25
IO126NB3F11	AA22
IO126PB3F11	AA23
IO127NB3F11	AC26

BG729	
AX1000 Function	Pin Number
IO127PB3F11	AC27
IO128NB3F11	Y20
IO128PB3F11	W19
Bank 4	
IO129NB4F12	AA20
IO129PB4F12	Y21
IO130NB4F12	AB22
IO130PB4F12	AB23
IO131NB4F12	AC22
IO131PB4F12	AC23
IO132NB4F12	AD23
IO132PB4F12	AD24
IO133NB4F12	AF23
IO133PB4F12	AE23
IO134NB4F12	AC21
IO134PB4F12	AB21
IO135NB4F12	AC20
IO135PB4F12	AB20
IO136NB4F12	AD21
IO136PB4F12	AD22
IO137NB4F12	Y19
IO137PB4F12	AA19
IO138NB4F12	AE21
IO138PB4F12	AE22
IO139NB4F13	AF21
IO139PB4F13	AF22
IO140NB4F13	AG22
IO140PB4F13	AG23
IO141NB4F13	Y18
IO141PB4F13	AA18
IO142NB4F13	AE20
IO142PB4F13	AD20
IO143NB4F13	AG20
IO143PB4F13	AG21
IO144NB4F13	AC19
IO144PB4F13	AB19
IO145NB4F13	AD18

BG729	
AX1000 Function	Pin Number
IO145PB4F13	AD19
IO146NB4F13	AC18
IO146PB4F13	AB18
IO147NB4F13	Y17
IO147PB4F13	AA17
IO148NB4F13	AF19
IO148PB4F13	AF20
IO149NB4F13	AC17
IO149PB4F13	AB17
IO150NB4F13	AE18
IO150PB4F13	AE19
IO151NB4F13	AA16
IO151PB4F13	Y16
IO152NB4F14	AG18
IO152PB4F14	AG19
IO153NB4F14	AC16
IO153PB4F14	AB16
IO154NB4F14	AF17
IO154PB4F14	AF18
IO155NB4F14	AB15
IO155PB4F14	AC15
IO156NB4F14	AE16
IO156PB4F14	AE17
IO157NB4F14	Y15
IO157PB4F14	AA15
IO158NB4F14	AG16
IO158PB4F14	AG17
IO159NB4F14/CLKEN	AF15
IO159PB4F14/CLKEP	AF16
IO160NB4F14/CLKFN	AD14
IO160PB4F14/CLKFP	AD15
Bank 5	
IO161NB5F15/CLKGN	AE14
IO161PB5F15/CLKGP	AE15
IO162NB5F15/CLKHN	AC13
IO162PB5F15/CLKHP	AD13
IO163NB5F15	Y14

FG256



Note

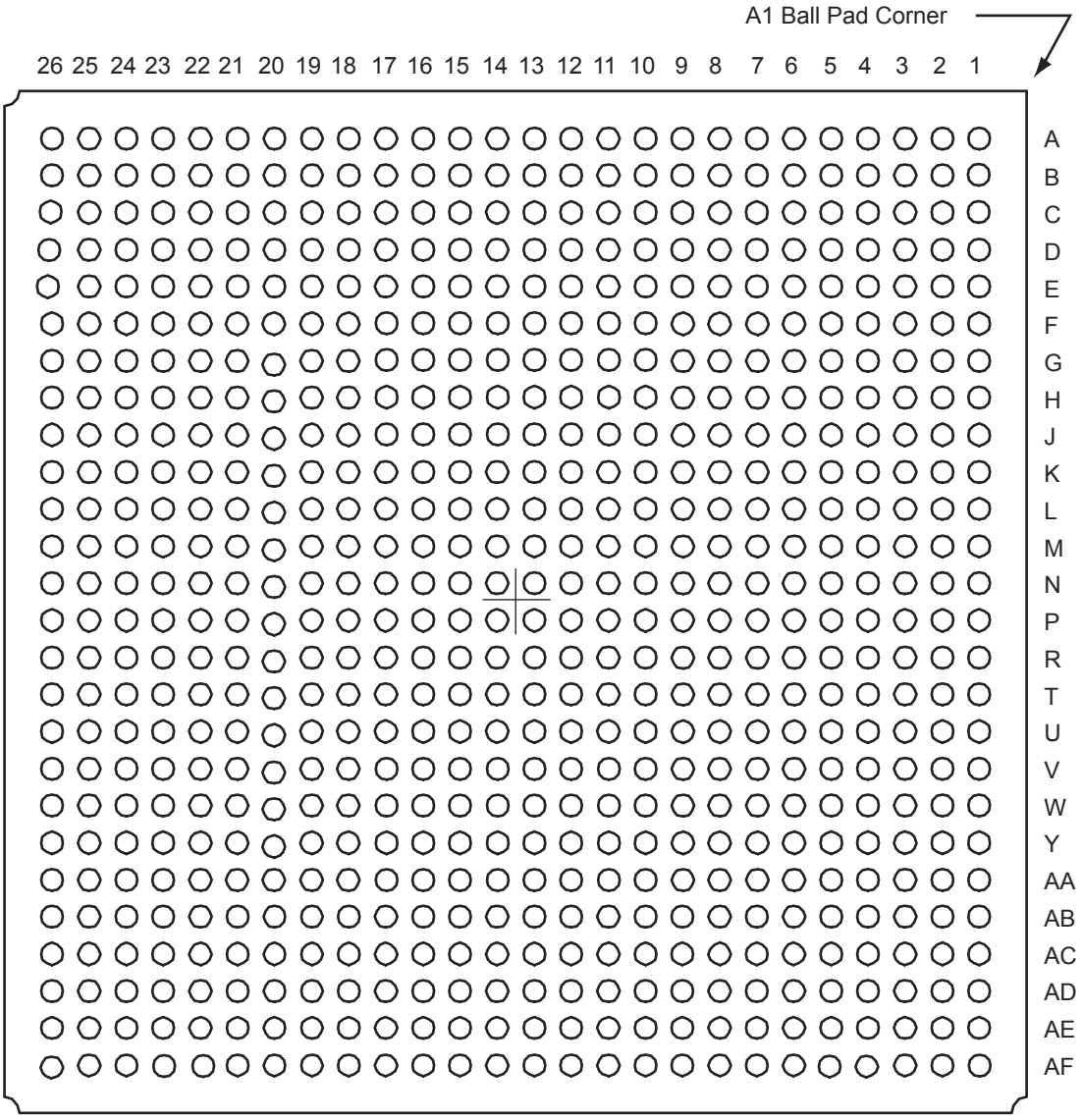
For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG484	
AX1000 Function	**Pin Number**
VCCPLA	F10
VCCPLB	G9
VCCPLC	D13
VCCPLD	G13
VCCPLE	U13
VCCPLF	T14
VCCPLG	W10
VCCPLH	T10
VCCDA	AB16
VCCDA	AB8
VCCDA	C10
VCCDA	C11
VCCDA	C14
VCCDA	D14
VCCDA	D5
VCCDA	F16
VCCDA	G12
VCCDA	L4
VCCDA	M18
VCCDA	T11
VCCDA	T17
VCCDA	U7
VCCDA	V14
VCCDA	V8
VCCIB0	A3
VCCIB0	B3
VCCIB0	H10
VCCIB0	H11
VCCIB0	H9
VCCIB1	A20
VCCIB1	B20
VCCIB1	H12
VCCIB1	H13
VCCIB1	H14
VCCIB2	C21

FG484	
AX1000 Function	**Pin Number**
VCCIB2	C22
VCCIB2	J15
VCCIB2	K15
VCCIB2	L15
VCCIB3	M15
VCCIB3	N15
VCCIB3	P15
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA20
VCCIB4	AB20
VCCIB4	R12
VCCIB4	R13
VCCIB4	R14
VCCIB5	AA3
VCCIB5	AB3
VCCIB5	R10
VCCIB5	R11
VCCIB5	R9
VCCIB6	M8
VCCIB6	N8
VCCIB6	P8
VCCIB6	Y1
VCCIB6	Y2
VCCIB7	C1
VCCIB7	C2
VCCIB7	J8
VCCIB7	K8
VCCIB7	L8
VCOMPLA	D10
VCOMPLB	G10
VCOMPLC	E12
VCOMPLD	G14
VCOMPLE	W13
VCOMPLF	T13

FG484	
AX1000 Function	**Pin Number**
VCOMPLG	V11
VCOMPLH	T9
VPUMP	D17

FG676



Note

For Package Manufacturing and Environmental information, visit Resource center at http://www.microsemi.com/soc/products/rescenter/package/index.html.

FG896	
AX2000 Function	**Pin Number**
IO303PB7F28	R1
IO304NB7F28	R7
IO304PB7F28	R6
IO306NB7F28	N2
IO306PB7F28	P2
IO307NB7F28	N3
IO307PB7F28	P3
IO308NB7F28	P9
IO308PB7F28	P8
IO309NB7F28	P4
IO309PB7F28	P5
IO310NB7F29	P7
IO310PB7F29	P6
IO311NB7F29	L1
IO311PB7F29	M1
IO312NB7F29	M5
IO312PB7F29	N5
IO313NB7F29	M4
IO313PB7F29	N4
IO315NB7F29	L2
IO315PB7F29	M2
IO316NB7F29	N7
IO316PB7F29	N6
IO317NB7F29	L3
IO317PB7F29	M3
IO318NB7F29	N8
IO318PB7F29	N9
IO320NB7F29	L6
IO320PB7F29	M6
IO321NB7F30	K4
IO321PB7F30	L4
IO322NB7F30	M8
IO322PB7F30	M7
IO323NB7F30	J1
IO323PB7F30	K1

FG896	
AX2000 Function	**Pin Number**
IO324NB7F30	K5
IO324PB7F30	L5
IO326NB7F30	G1*
IO326PB7F30	K2*
IO327NB7F30	J4
IO327PB7F30	J3
IO328NB7F30	L8
IO328PB7F30	L7
IO329NB7F30	G2
IO329PB7F30	H2
IO330NB7F30	G3
IO330PB7F30	H3
IO331NB7F30	K8
IO331PB7F30	K7
IO332NB7F31	J6
IO332PB7F31	K6
IO333NB7F31	D1
IO333PB7F31	D2
IO334NB7F31	G4
IO334PB7F31	H4
IO335NB7F31	F2
IO335PB7F31	F1
IO336NB7F31	H5
IO336PB7F31	J5
IO337NB7F31	E2
IO337PB7F31	E1
IO338NB7F31	H7
IO338PB7F31	J7
IO339NB7F31	F4
IO339PB7F31	F3
IO340NB7F31	F5
IO340PB7F31	G5
IO341NB7F31	G6
IO341PB7F31	H6
Dedicated I/O	

FG896	
AX2000 Function	**Pin Number**
GND	A13
GND	A18
GND	A2
GND	A23
GND	A29
GND	A8
GND	AA10
GND	AA21
GND	AA28
GND	AA3
GND	AB2
GND	AB22
GND	AB29
GND	AB9
GND	AC1
GND	AC30
GND	AE25
GND	AE6
GND	AF26
GND	AF5
GND	AG27
GND	AG4
GND	AH10
GND	AH15
GND	AH16
GND	AH21
GND	AH28
GND	AH3
GND	AJ1
GND	AJ2
GND	AJ22
GND	AJ29
GND	AJ30
GND	AJ9
GND	AK13

FG1152	
AX2000 Function	Pin Number
IO155PB3F14	AC29
IO156NB3F14	AE30
IO156PB3F14	AD30
IO157NB3F14	AC26
IO157PB3F14	AB26
IO158NB3F14	AH33
IO158PB3F14	AG33
IO159NB3F14	AD27
IO159PB3F14	AC27
IO160NB3F14	AG32
IO160PB3F14	AF32
IO161NB3F15	AG31
IO161PB3F15	AF31
IO162NB3F15	AF29
IO162PB3F15	AE29
IO163NB3F15	AE28
IO163PB3F15	AD28
IO164NB3F15	AG30
IO164PB3F15	AF30
IO165NB3F15	AE26
IO165PB3F15	AD26
IO166NB3F15	AJ30
IO166PB3F15	AH30
IO167NB3F15	AG28
IO167PB3F15	AF28
IO168NB3F15	AF27
IO168PB3F15	AE27
IO169NB3F15	AH29
IO169PB3F15	AG29
IO170NB3F15	AD25
IO170PB3F15	AC25
Bank 4	
IO171NB4F16	AP29
IO171PB4F16	AN29
IO172NB4F16	AH26

FG1152	
AX2000 Function	Pin Number
IO172PB4F16	AH27
IO173NB4F16	AJ27
IO173PB4F16	AJ28
IO174NB4F16	AL27
IO174PB4F16	AL28
IO175NB4F16	AM28
IO175PB4F16	AM29
IO176NB4F16	AG25
IO176PB4F16	AG26
IO177NB4F16	AK26
IO177PB4F16	AK27
IO178NB4F16	AF25
IO178PB4F16	AE25
IO179NB4F16	AP28
IO179PB4F16	AN28
IO180NB4F16	AJ25
IO180PB4F16	AJ26
IO181NB4F17	AM26
IO181PB4F17	AM27
IO182NB4F17	AF24
IO182PB4F17	AE24
IO183NB4F17	AH24
IO183PB4F17	AH25
IO184NB4F17	AG23
IO184PB4F17	AG24
IO185NB4F17	AL25
IO185PB4F17	AL26
IO186NB4F17	AP25
IO186PB4F17	AP26
IO187NB4F17	AK24
IO187PB4F17	AK25
IO188NB4F17	AF23
IO188PB4F17	AE23
IO189NB4F17	AN24
IO189PB4F17	AM24

FG1152	
AX2000 Function	Pin Number
IO190NB4F17	AH22
IO190PB4F17	AH23
IO191NB4F17	AJ23
IO191PB4F17	AJ24
IO192NB4F17	AG21
IO192PB4F17	AG22
IO193NB4F18	AP23
IO193PB4F18	AP24
IO194NB4F18	AN22
IO194PB4F18	AN23
IO195NB4F18	AM23
IO195PB4F18	AL23
IO196NB4F18	AF21
IO196PB4F18	AF22
IO197NB4F18	AL22
IO197PB4F18	AM22
IO198NB4F18	AE21
IO198PB4F18	AE22
IO199NB4F18	AJ21
IO199PB4F18	AJ22
IO200NB4F18	AK21
IO200PB4F18	AK22
IO201NB4F18	AM21
IO201PB4F18	AL21
IO202NB4F18	AE20
IO202PB4F18	AD20
IO203NB4F19	AN21
IO203PB4F19	AP21
IO204NB4F19	AP20
IO204PB4F19	AN20
IO205NB4F19	AN19
IO205PB4F19	AP19
IO206NB4F19	AG20
IO206PB4F19	AF20
IO207NB4F19	AL19

CG624	
AX2000 Function	**Pin Number**
Bank 0	
IO00NB0F0	D7*
IO00PB0F0	E7*
IO01NB0F0	G7
IO01PB0F0	G6
IO02NB0F0	B5
IO02PB0F0	B4
IO04PB0F0	C7
IO05NB0F0	F8
IO05PB0F0	F7
IO06NB0F0	H8
IO06PB0F0	H7
IO11NB0F0	J8
IO11PB0F0	J7
IO12PB0F1	B6
IO13NB0F1	E9*
IO13PB0F1	D8*
IO15NB0F1	C9
IO15PB0F1	C8
IO16NB0F1	A5
IO16PB0F1	A4
IO17NB0F1	D10
IO17PB0F1	D9
IO18NB0F1	A7
IO18PB0F1	A6
IO19NB0F1	G9
IO19PB0F1	G8
IO20PB0F1	B7
IO23NB0F2	F10
IO23PB0F2	F9
IO26NB0F2	C11*
IO26PB0F2	B8*

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO27NB0F2	H10
IO27PB0F2	H9
IO28NB0F2	A9
IO28PB0F2	B9
IO30NB0F2	B11
IO30PB0F2	B10
IO31NB0F2	E11
IO31PB0F2	F11
IO33NB0F2	D12
IO33PB0F2	D11
IO34NB0F3	A11
IO34PB0F3	A10
IO37NB0F3	J13
IO37PB0F3	K13
IO38NB0F3	H11
IO38PB0F3	G11
IO40PB0F3	B12
IO41NB0F3/HCLKAN	G13
IO41PB0F3/HCLKAP	G12
IO42NB0F3/HCLKBN	C13
IO42PB0F3/HCLKBP	C12
Bank 1	
IO43NB1F4/HCLKCN	G15
IO43PB1F4/HCLKCP	G14
IO44NB1F4/HCLKDN	B14
IO44PB1F4/HCLKDP	B13
IO45NB1F4	H13
IO47NB1F4	D14
IO47PB1F4	C14
IO48NB1F4	A16
IO48PB1F4	A15
IO49PB1F4	H15

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
IO51NB1F4	E15
IO51PB1F4	F15
IO52NB1F4	A17
IO55NB1F5	G16
IO55PB1F5	H16
IO56NB1F5	A20
IO56PB1F5	A19
IO57NB1F5	D16
IO57PB1F5	D15
IO58NB1F5	A22
IO58PB1F5	A21
IO59NB1F5	F16
IO61NB1F5	G17
IO61PB1F5	H17
IO62NB1F5	B17
IO62PB1F5	B16
IO63NB1F5	H18
IO65NB1F6	C17
IO66PB1F6	B18
IO67NB1F6	J18
IO67PB1F6	J19
IO68NB1F6	B20
IO68PB1F6	B19
IO69NB1F6	E17
IO69PB1F6	F17
IO70NB1F6	B22
IO70PB1F6	B21
IO71PB1F6	G18
IO73NB1F6	G19
IO74NB1F6	C19
IO74PB1F6	C18
IO75NB1F6	D18

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

4 – Datasheet Information

List of Changes

The following table lists critical changes that were made in the current version of the document.

Revision	Changes	Page
Revision 18 (March 2012)	Table 2-1 • Absolute Maximum Ratings was updated to correct the maximum DC core supply voltage (VCCA) from 1.6 V to 1.7 V (SAR 36786). The maximum input voltage (VI) was corrected from 3.75 V to 4.1 V (SAR 35419).	2-1
	Values for tristate leakage current IOZ, and IIH and IIL were added to Table 2-3 • Standby Current (SARs 35774, 32021).	2-2
	Figure 2-2 • VCCPLX and VCOMPLX Power Supply Connect was updated to correct the units for the resistance from "W" to Ω (SAR 36415).	2-9
	In the Introduction to the "User I/Os" section, the following sentence was added to clarify the slew rate setting (SAR 34943): The slew rate setting is effective for both rising and falling edges.	2-11
	Figure 2-3 • Use of an External Resistor for 5 V Tolerance was revised to show the VCCI and GND clamp diodes. The explanatory text above the figure was revised as well (SAR 34942).	2-13
	EQ 3 for 5 V tolerance was corrected to change Vdiode from 0.6 V to 0.7 V (SAR 36786).	2-13
	Additional information was added to the "Using the Weak Pull-Up and Pull-Down Circuits" section to clarify how the weak pull-up and pull-down resistors are physically implemented (SAR 34945).	2-17
	The description for the C_{INCLK} parameter in Table 2-18 • Input Capacitance was changed from "Input capacitance on clock pin" to "Input capacitance on HCLK and RCLK pin" (SAR 34944).	2-21
	Table 2-19 • I/O Input Rise Time and Fall Time* is new (SAR 34942).	2-21
	The minimum VIL for 1.5 V LVCMOS and PCI was corrected from –0.5 to –0.3 in Table 2-29 • DC Input and Output Levels and Table 2-33 • DC Input and Output Levels (SAR 34358).	2-38, 2-40
	Support for simulating the GCLR/ GPSET feature in the Axcelerator Family was added in Libero software v9.0 SPI1. Reference to the section explaining this in the *Antifuse Macro Library Guide* was added to the "R-Cell" section (SAR 26413).	2-58
	The enable signal in Figure 2-32 • R-Cell Delays was corrected to show it is active low rather than active high (SAR 34946).	2-59
Revision 17 (September 2011)	The versioning system for datasheets has been changed. Datasheets are assigned a revision number that increments each time the datasheet is revised. The "Axcelerator Family Device Status" table indicates the status for each device in the device family.	iii
	The "Features" section, "Programmable Interconnect Element" section, and "Security" section were revised to clarify that although no existing security measures can give an absolute guarantee, Microsemi FPGAs implement the best security available in the industry (SAR 32865).	i, 1-1, 2-108